

HZM6.2ZMFA

Silicon Planar Zener Diode for Surge Absorb

REJ03G1207-0100 (Previous: ADE-208-1515) Rev.1.00 Jun 08, 2005

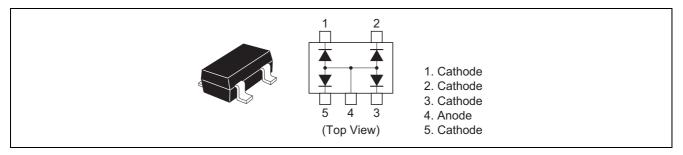
Features

- HZM6.2ZMFA has four devices in a monolithic, and can absorb surge.
- Low capacitance (C = 8.5 pF max) and can protect ESD of signal line.
- MPAK-5 Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZM6.2ZMFA	62N	MPAK-5	PLSP0005ZC-A (MPAK-5)

Pin Arrangement





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Symbol	Value	Unit
Pd *	200	mW
Tj	150	°C
Tstg	-55 to +150	°C
	Pd * Tj	Pd * 200 Tj 150

Note: Four device total, See Fig.2.

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

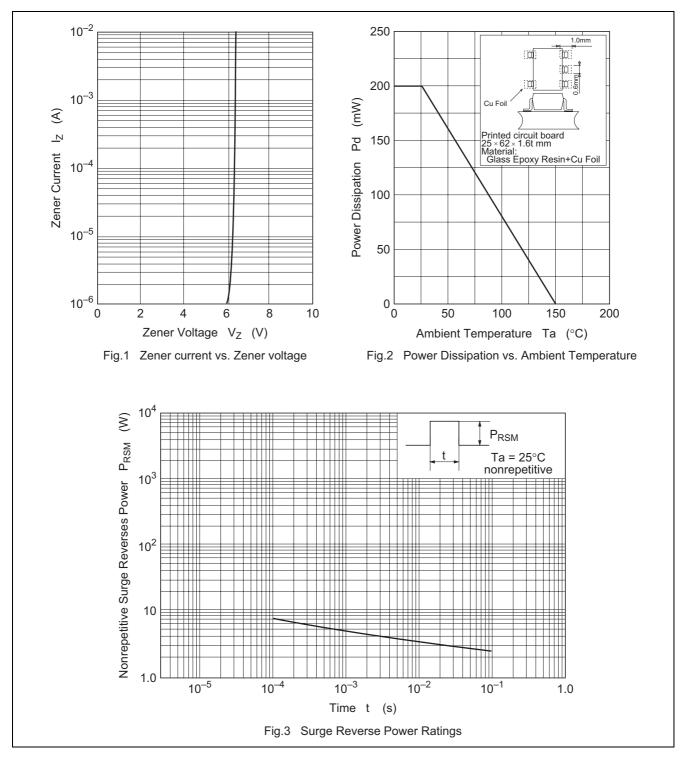
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	Vz	5.90	—	6.50	V	$I_Z = 5 \text{ mA}, 40 \text{ ms pulse}$
Reverse current	I _R	—	—	3	μA	V _R = 5.5 V
Capacitance	С	—	—	8.5	pF	V _R =0 V, f = 1 MHz
Dynamic resistance	r _d	—	—	60	Ω	I _Z = 5 mA
ESD-Capability * ²	—	13	_	—	kV	C = 150 pF, R = 330 Ω , Both forward and reverse direction 10 pulse.

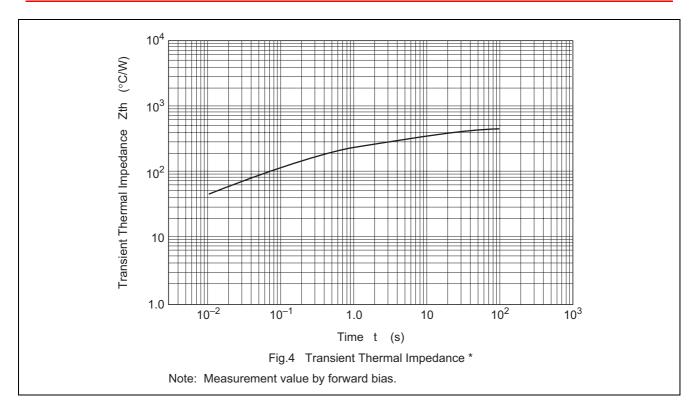
Notes: 1. Per one device

2. Failure criterion ; I_R > 3 μA at V_R = 5.5 V.



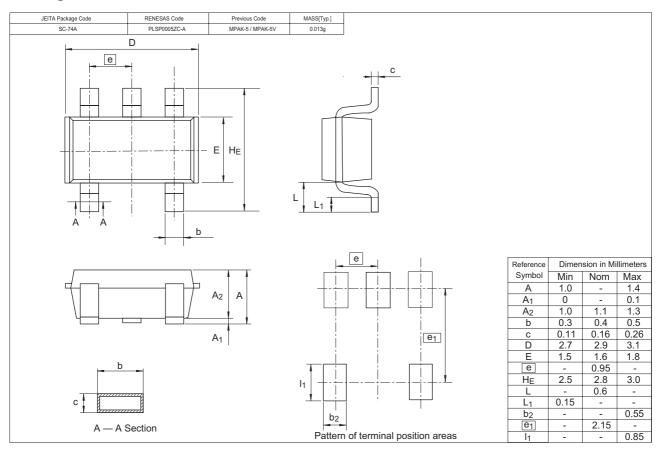
Main Characteristic







Package Dimensions





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